

## Product Change Notification / NTDO-10FDY0203

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14-Sep-2021

# **Product Category:**

Linear Op Amps

# **PCN Type:**

Manufacturing Change

# **Notification Subject:**

CCB 3064.003 Final Notice: Qualification of new lead frame design (lead lock) for selected MCP6042 device family available in 8L SOIC (.150in) package at MTAI assembly site.

# **Affected CPNs:**

NTDO-10FDYO203\_Affected\_CPN\_09142021.pdf NTDO-10FDYO203\_Affected\_CPN\_09142021.csv

## **Notification Text:**

PCN Status: Final notification.

PCN Type:Manufacturing Change

Microchip Parts Affected:Please open one of the files found in the Affected CPNs section.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

**Description of Change:**Qualification of new lead frame design (lead lock) for selected MCP6042 device family available in 8L SOIC (.150in) package at MTAI assembly site.

### Pre and Post Change Summary:

	Pre Change	Post Change				
Assembly Location	Microchip Technology Thailand (MTAI) (HQ)	Microchip Technology Thailand (MTAI) (HQ)				

Wire material	Au	Au				
Die attach material	8390A	8390A				
Molding compound material	G600	G600				
Lead frame material	CDA194	CDA194				
Lead Lock	No	Yes				
Lead frame DAP Surface Prep	Ag	Bare Cu				
Lead frame Comparison	Please see attached pre and post change summary					

### Impacts to Data Sheet:None

Change Impact:None

**Reason for Change:**To reduce the delamination and further improve device reliability by qualifying new lead frame design with lead lock.

**Change Implementation Status:**In Progress

**Estimated First Ship Date:** 

October 3, 2021 (date code: 2141)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

### Time Table Summary:

		Septe	mber	2021			Oct	ober 2	:021	
Workweek	3 6	3 7	3 8	3 9	4 0	4 1	4 2	43	4 4	45
Qual Report Availability			Χ							
Final PCN Issue Date			Χ							
Estimated Implementation Date						Х				

Method to Identify Change:Traceability code

Qualification Report:Please open the attachments included with this PCN labeled as PCN\_#\_Qual\_Report.

**Revision History:** 

September 14, 2021: Issued final notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

## Attachments:

PCN\_NTDO-10FDYO203\_Pre and Post Change Summary.pdf PCN\_NTDO-10FDYO203\_Qual Report.pdf

Please contact your local Microchip sales office with questions or concerns regarding this notification.

### **Terms and Conditions:**

If you wish to <u>receive Microchip PCNs via email</u> please register for our PCN email service at our <u>PCN</u> home page select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the <u>PCN FAQ</u> section.

If you wish to <u>change your PCN profile, including opt out,</u> please go to the <u>PCN home page</u> select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

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Affected Catalog Part Numbers (CPN)				
MCP6042-E/SNVAO MCP6042T-E/SNVAO				
Date: Tuesday, September 14, 2021				